

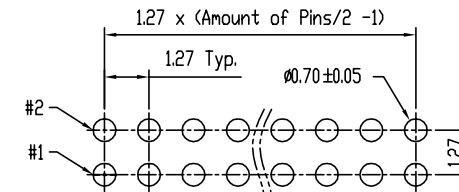
NOTE:

- MATERIAL:
HOUSING: HIGH TEMP THERMAL PLASTIC, UL94-V0
TERMINAL: COPPER ALLOY
- FINISH:
TERMINAL: GOLD AT CONTACT,
G/F OVER 1um(40u") MIN Ni OVER ALL
- SPEC.:
PRODUCT SPEC: GS-12-629
PACKING SPEC: GS-14-1517
- THE HSG. WILL WITHSTAND EXPOSURE TO 260°C
PEAK TEMP. FOR 10 SEC. IN A WAVE SOLDER APPLICATION.
- MATING SIDE LENGTH: 2.50MM MIN.

6. PRODUCT NUMBERING:

200218 2 3 - XXX XX X X LF

LEAD FREE
PLATING:
1:G/F ALL OVER
4:0.25um(10U")GOLD AT CONTACT
8:0.76um(30U") GOLD AT CONTACT
PACKING
T: TUBE
PIN COUNT
06, 08, ..., 98, A0
(EVERY EVEN PIN)
STACK HEIGHT "K"
EXAMPLE: 045=4.5MM
IN 0.5MM INCREMENT



Recommended P.C.B. Layout(TH)
Layout Tolerance = ± 0.05 mm

mat'l. code		surface <input checked="" type="checkbox"/> ISO1302 tolerance <input checked="" type="checkbox"/> ISO1101 <input type="checkbox"/> ISO406		projection	product family MINITEK
ltr	ecn no	dr	date	tolerances unless otherwise specified	title 1.27X1.27MM BTB STACK HDR VT. TH
A	-	ZK	03/23/12	MM	
				angles	scale 5:1
				0°±2'	
				dr HU, ZK 03/23/12	dwg no sheet 1 of 1 size 20021823 A4
				engr HU, ZK 03/23/12	
				chr BIAN, RICK 03/23/12	type Product Customer Drawing
				appd BIAN, RICK 03/23/12	
sheet index	revision sheet	A	1		